

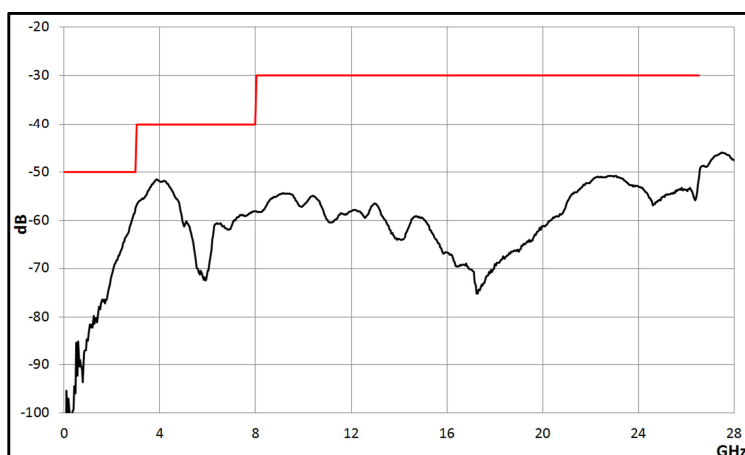
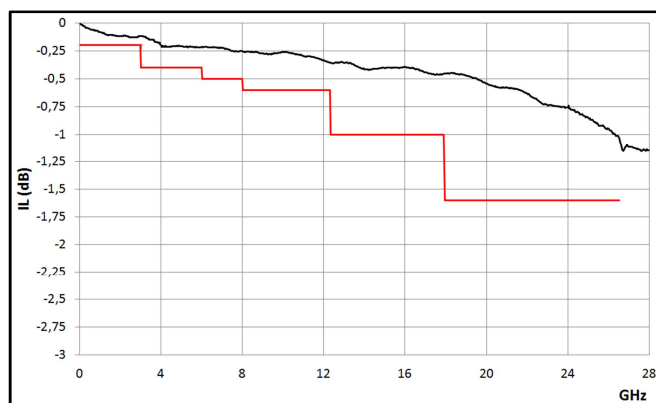
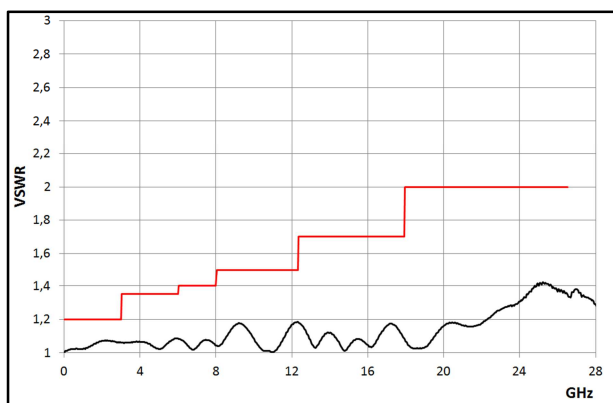
RF PERFORMANCES (1)

Frequency Range (GHz)		V.S.W.R	IL	Isolation (min) dB		Average power W	Third order Inter modulation	Impedance
		(max)	(max) dB	switch alone	switch+board layout (1)	hot switching		Ohms
DC – 8 DC – 18 DC – 26.5	DC – 3	1.20	0.20	50	50	40	-110 dBc Typical @ 1730 MHz (2 carriers 20W)	50
	3 – 6	1.35	0.40	40	40	25		
	6 – 8	1.40	0.50	40	40	5		
	8 – 12.4	1.50	0.60	40	30	3		
	12.4 – 18	1.70	1.00	40	30	1		
	18 – 26.5	2.00	1.60	40	30	1		

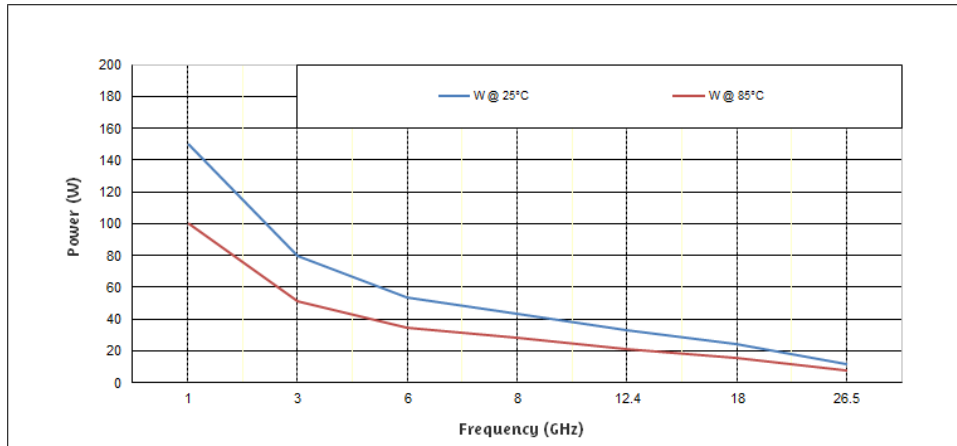
(1)  : at high frequency, manual soldering may generate spikes and RF characteristics degradation, due to air gaps between PC board and relay ground.

TYPICAL RF PERFORMANCE - MEASUREMENT METHOD USING UOSM 2.92mm CALIBRATION

2.92mm UOSM calibration is performed to extract RF performances of SMT relay. **VSWR** values are those of the complete evaluation board (Relay + coaxial connectors and microstrip access lines). **Insertion loss** values are those of the relay by subtracting the loss of an equivalent length of microstrip access line.



RF POWER RATING FOR COLD SWITCHING USE



RELAY PACKAGING

For relays soldered on test fixture: individual packaging

For not soldered relays:

For quantities up to 50 relays: packaged in tape without reel

For upper quantities: packaged in tape and reel, maximum **200** relays per reel

ACCORDING TO IEC 286-3 STANDARD

MATERIALS

Reel : polyester

Carrier tape : PVC

Cover tape : polyester

